



# 100% Material Declaration Data Sheet FFG1738

PK216 (v1.0) January 15, 2007

Material Declaration Data Sheet

**Average Weight: 15.9800 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.004160</b>	<b>0.026%</b>
	Silicon	7440-21-3	100.00		0.004160	
<b>Solder Bump</b>					<b>0.032250</b>	<b>0.202%</b>
	Tin	7440-31-5	63.00		0.020318	
	Lead	7439-92-1	37.00		0.011933	
<b>Underfill</b>					<b>0.100000</b>	<b>0.626%</b>
	Silica	60676-86-0	54.50		0.054500	
	Epoxy Resin A	25068-38-6	2.50		0.002500	
	Epoxy Resin B	9003-36-5	25.00		0.025000	
	Phenolic Resin	9003-35-4	15.0		0.015000	
	Carbon Black	1333-86-4	0.50		0.000500	
	Additive	2530-83-8	2.50		0.002500	
<b>Heat Spreader</b>					<b>7.350000</b>	<b>45.995%</b>
	Copper	7440-50-8	99.60		7.320600	
	Nickel	7440-02-0	0.40		0.029400	
<b>Heat Sink Adhesive</b>					<b>0.260000</b>	<b>1.627%</b>
	Organopolysiloxane mixture	N/A	10.00		0.260000	
<b>Substrate</b>					<b>6.781720</b>	<b>42.439%</b>
	Copper	7440-50-8	46.49	Metal Layer	3.152822	
	Nickel	7440-02-0	0.52	Metal Layer	0.035265	
	Gold	7440-57-5	0.11	Metal Layer	0.007460	
	Glass fiber	N/A	10.40		0.705299	
	Halogen fire retardant	N/A	5.32		0.360788	
	BT (CORE)	N/A	28.56		1.936859	
	Solder Mask	N/A	8.60		0.583228	
<b>Solder Balls</b>					<b>1.451870</b>	<b>9.086%</b>
	Tin	7440-31-5	95.50		1.386536	
	Silver	7440-22-4	4.00		0.058075	
	Copper	7440-50-8	0.50		0.007259	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
1/15/07	1.0	Initial release.